

CLAIM AMENDMENTS:

Claim 1 (Currently Amended): A semiconductor device, comprising:

a semiconductor substrate having a circuit forming surface, and having a plurality of electrode pads provided on the circuit forming surface, said electrode pads being disposed to surround an area of the circuit forming surface;

a semiconductor element mounted within the area of the circuit forming surface;

a plurality of adhesive lines adapted for use as reference lines, said adhesive lines being disposed under the semiconductor element and on the circuit forming surface, and being respectively provided at positions corresponding to at least three corners of the semiconductor element, said adhesive lines being adapted for use as a reference for determining a correct placement of the semiconductor element within the area of the circuit forming surface, said adhesive lines adhering said semiconductor element to the circuit forming surface of said semiconductor substrate; and

a sealing resin that seals said semiconductor element;

wherein the reference lines extend beyond and outside an area that is sealed by said sealing resin.

Claims 2-20 (Cancelled).

Claim 21 (New): The semiconductor device recited in claim 1, wherein a portion of the reference lines that extends beyond and outside the area that is sealed by said sealing resin is not covered by said sealing resin.